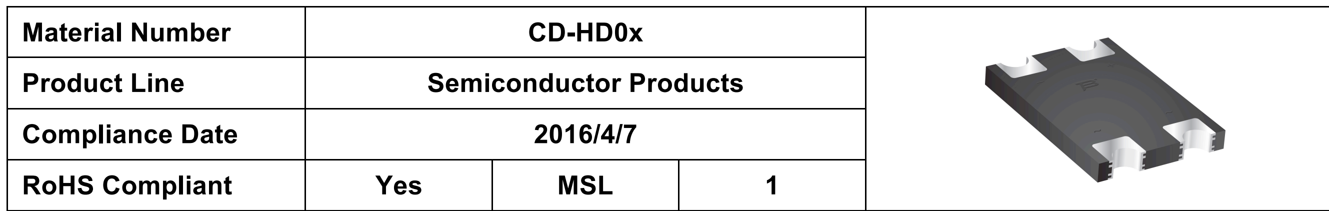
MATERIAL DECLARATION SHEET



Material Number	CD-HD0x		
Product Line	Semiconductor Products		
Compliance Date	2016/4/7		
RoHS Compliant	Yes	MSL	1

No.	Construction Element (subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	FRP	Others	42.5	Continuous filament glass fibers	65997-17-3	43	26.10700%	60.7140%
				Copper	7440-50-8	14	8.50000%	
				Non-Hazardous cured resin	Proprietary	43	26.10700%	
2	Epoxy	Plastic	24	Silicon Dioxide	7631-86-9	55	18.8573%	34.2860%
				Epoxy resin	9003-36-5	45	15.4287%	
3	Solder Cream	Metal	0.3	Lead[2]	7439-92-1	88	0.37717%	0.4286%
				Tin	7440-31-5	10	0.04286%	
				Silver	7440-22-4	2	0.00857%	
4	Dice	Others	1.8	Silicon	7440-21-3	97.98	2.51945%	2.5714%
				Titanium	7440-32-6	0.01	0.00026%	
				Nickel	7440-02-0	0.01	0.00026%	
				Silver	7440-22-4	2	0.05143%	
5	Terminal Plating	Metal	1.4	Tin	7440-31-5	99.9	1.99800%	2.0000%
				Misc, not to declare	-	0.1	0.00200%	
		Total weight	70					

This Document was updated on: 2016/4/7

Important remarks:

1. **It is the responsibility of the user to verify they are accessing the latest version.**
2. **Excepted for RoHS 7(a) - Lead in high temp solders**

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